

Package: QFN, 6mmx6mm

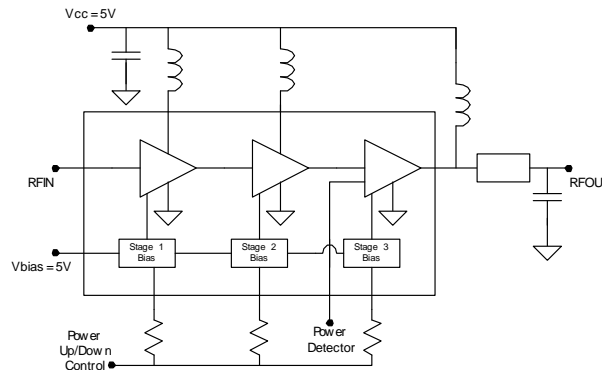


### Product Description

RFMD's SZM-2066Z is a high linearity class AB Heterojunction Bipolar Transistor (HBT) amplifier housed in a low-cost surface-mountable plastic Q-FlexN multi-chip module package. This HBT amplifier is made with InGaP on GaAs device technology and fabricated with MOCVD for an ideal combination of low cost and high reliability. This product is specifically designed as a final or driver stage for 802.16 and 802.11b/g equipment in the 2.4 GHz to 2.7 GHz bands. It can run from a 3V to 5V supply. The external output match and bias adjustability allows load line optimization for other applications or over narrower bands. It features an output power detector, on/off power control and high RF overdrive robustness. A 20dB step attenuator feature can be utilized by switching the second stage Power up/down control.

**Optimum Technology Matching® Applied**

- GaAs HBT
- GaAs MESFET
- InGaP HBT
- SiGe BiCMOS
- Si BiCMOS
- SiGe HBT
- GaAs pHEMT
- Si CMOS
- Si BJT
- GaN HEMT
- InP HBT
- RF MEMS
- LDMOS



### Features

- $P_{1dB} = 33.5 \text{ dBm}$  at 5V
- Three Stages of Gain: 37 dB
- 802.11g 54 Mb/s Class AB Performance
- $P_{OUT} = 26 \text{ dBm}$  at 2.5% EVM, VCC 5V, 690mA
- Active Bias with Adjustable Current
- On-Chip Output Power Detector
- Low Thermal Resistance
- Power Up/Down Control  $< 1\mu\text{s}$
- Attenuator Step 20dB at  $V_{PC2} = 0V$

### Applications

- 802.16 WiMAX Driver or Output Stage
- 802.11b/g WiFi, WiFi

| Parameter                       | Specification |            |       | Unit                        | Condition  |
|---------------------------------|---------------|------------|-------|-----------------------------|--|
|                                 | Min.          | Typ.       | Max.  |                             |  |
| Frequency of Operation          | 2500          |            | 2700  | MHz                         |  |
| Output Power at 1dB Compression | 32.0          | 33.5       |       | dBm                         | 2.7 GHz  |
| Small Signal Gain               | 32.2          | 33.7       |       | dB                          | 2.7 GHz  |
| EVM                             |               | 2.5        |       | %                           | 2.7 GHz, 802.11g 54 Mb/s at $P_{OUT} = 26 \text{ dBm}$ |
| Third Order Suppression         |               | -45.0      | -40.0 | dBc                         | 2.7 GHz, $P_{OUT} = 23 \text{ dBm}$ per tone           |
| Noise Figure                    |               | 7.7        |       | dB                          | 2.7 GHz  |
| Worst Case Input Return Loss    | 7.5           | 10.5       |       | dB                          | 2.5 GHz to 2.7 GHz                                     |
| Worst Case Output Return Loss   | 12.5          | 15.5       |       | dB                          | 2.5 GHz to 2.7 GHz                                     |
| Output Voltage Range            |               | 0.9 to 1.8 |       | V                           | $P_{OUT} = 10 \text{ dBm}$ to $33 \text{ dBm}$         |
| Quiescent Current               | 454           | 583        | 659   | mA                          | $V_{CC} = 5V$  |
| Power Up Control Current        |               | 4.0        |       | mA                          | $V_{PC} = 5V, I_{VPC1} + I_{VPC2} + I_{VPC3}$          |
| VCC Leakage Current             |               |            | 100   | $\mu\text{A}$               | $V_{CC} = 5V, V_{PC} = 0V$                             |
| Thermal Resistance              |               | 12.0       |       | $^{\circ}\text{C}/\text{W}$ | junction - lead  |

Test Conditions:  $Z_0 = 50\Omega, V_{CC} = 5V, I_Q = 583 \text{ mA}, T_{BP} = 30^{\circ}\text{C}$

## Absolute Maximum Ratings

| Parameter  | Rating      | Unit |
|--|-------------|------|
| VC3 Collector Bias Current ( $I_{VC3}$ )                         | 1500        | mA   |
| VC2 Collector Bias Current ( $I_{VC2}$ )                         | 500         | mA   |
| VC1 Collector Bias Current ( $I_{VC1}$ )                         | 150         | mA   |
| *** Device Voltage ( $V_D$ )                                     | 9.0         | V    |
| Power Dissipation  | 6           | W    |
| ***Max CW RF output Power for 50W continuous long term operation | 30          | dBm  |
| Max CW RF output Power for 50Ω output load                       | 26          | dBm  |
| Max CW RF Input Power for 10:1 VSWR out load                     | 5           | dBm  |
| Storage Temperature Range  | -40 to +150 | °C   |
| Operating Temp Range ( $T_L$ )                                   | -40 to +85  | °C   |
| Operating Junction Temperature ( $T_J$ )                         | +150        | °C   |
| ESD Rating - Human Body Model                                    | 1000        | V    |

\*\*\*With specified application circuit

\*\*\*No RF Drive

Operation of this device beyond any one of these limits may cause permanent damage. For reliable continuous operation, the device voltage and current must not exceed the maximum operating values specified in the table on page one.

Bias Conditions should also satisfy the following expression:

$$I_D V_D < (T_J - T_L) / R_{TH, j1}$$



Caution! ESD sensitive device.

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability. Specified typical performance or functional operation of the device under Absolute Maximum Rating conditions is not implied.

RoHS status based on EU Directive 2002/95/EC (at time of this document revision).

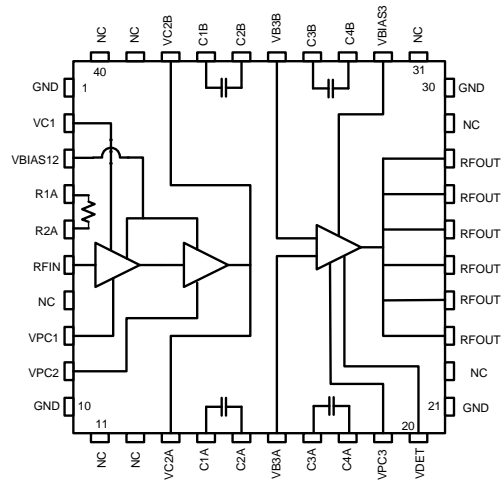
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## Typical Performance with appropriate app circuit ( $V_{CC}=5V$ , $I_{CQ}=583mA$ , \*802.11g 54 Mb/s 64QAM)

| Parameter                         | Unit | **2.4 GHz | 2.5 GHz | 2.6 GHz | 2.7 GHz |
|-----------------------------------|------|-----------|---------|---------|---------|
| Gain @ $P_{OUT}=26dBm$            | dB   | 37.5      | 36.9    | 36.5    | 34.6    |
| P1dB                              | dBm  | 34.6      | 33.5    | 33.5    | 33.9    |
| $P_{OUT}$ @ 2.5% EVM*             | dBm  | 27.0      | 26.0    | 26.0    | 26.5    |
| Current @ $P_{OUT}$ 2.5% EVM*     | mA   | 703       | 710     | 700     | 712     |
| Input Return Loss                 | dB   | -12.1     | -11.5   | -10.8   | -10.5   |
| Output Return Loss                | dB   | -27       | -15.6   | -28     | -18.5   |
| Step Attenuation ( $V_{PC2}=0V$ ) | dB   | 27        | 27      | 26      | 25      |

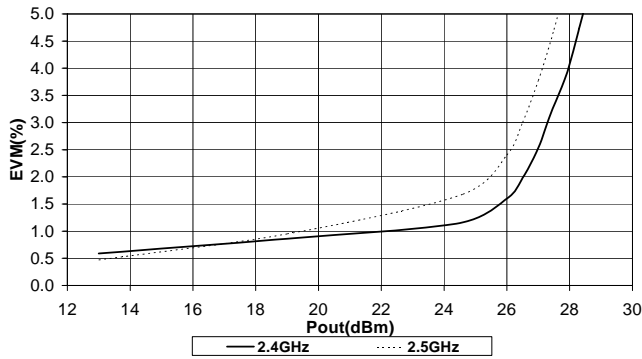
Test Conditions: \*\*Measured with 2.4GHz to 2.5GHz Application circuit.

## Simplified Device Schematic

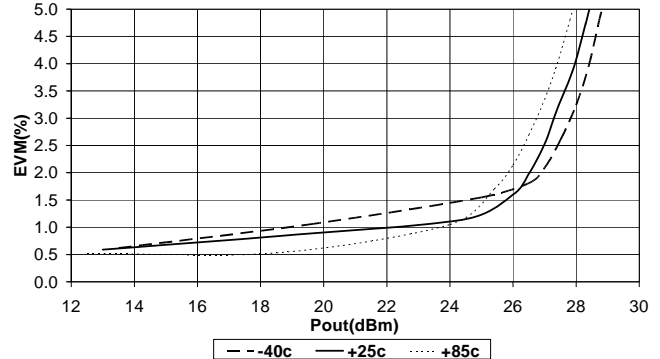


Measured 2.4GHz to 2.5GHz Application Circuit Data ( $V_{CC}=V_{PC}=5.0V$ ,  $I_Q=556mA$ ,  $T=25^\circ C$ )

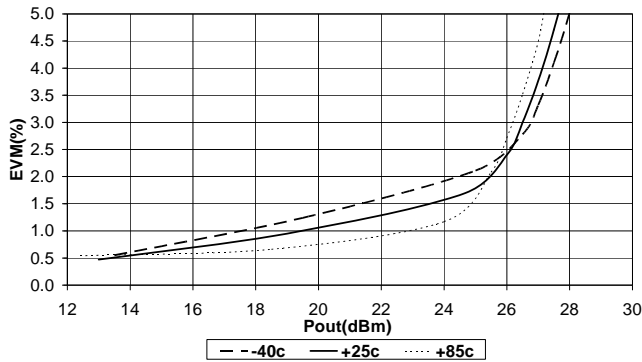
**EVM vs Pout T=+25c**  
802.11g, OFDM 54Mb/S, 64QAM



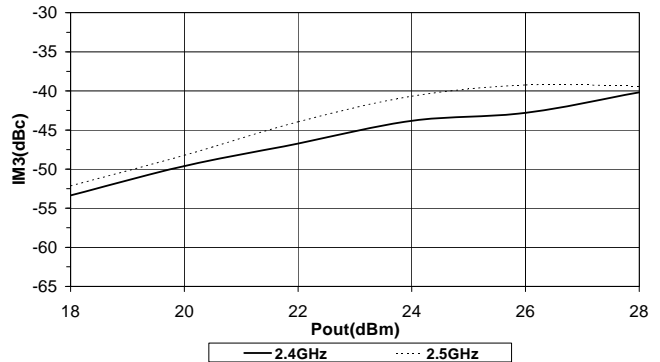
**EVM vs Pout F=2.4GHz**  
802.11g, OFDM 54Mb/S, 64QAM



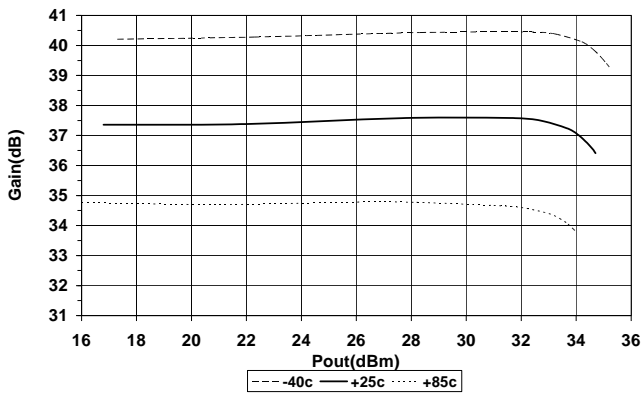
**EVM vs Pout F=2.5GHz**  
802.11g, OFDM 54Mb/S, 64QAM



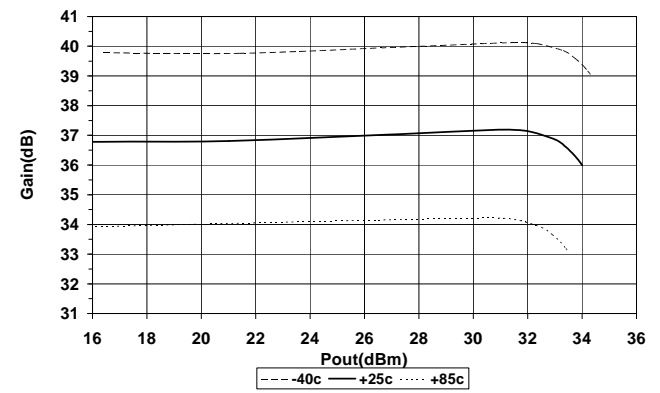
**IM3 vs Pout (2 Tone Avg.), T=+25c**  
Tone Spacing = 1MHz



**Typical Gain vs Pout, F=2.4GHz**

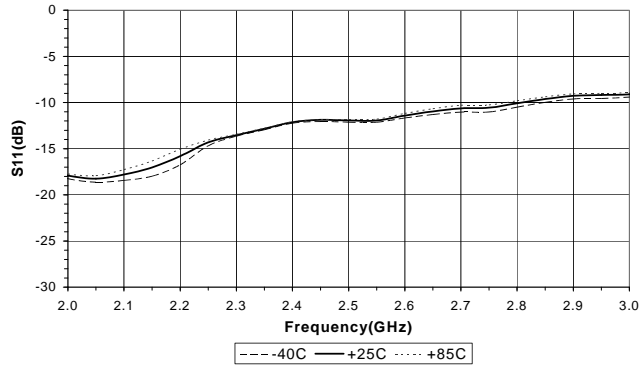


**Typical Gain vs Pout, F=2.5GHz**

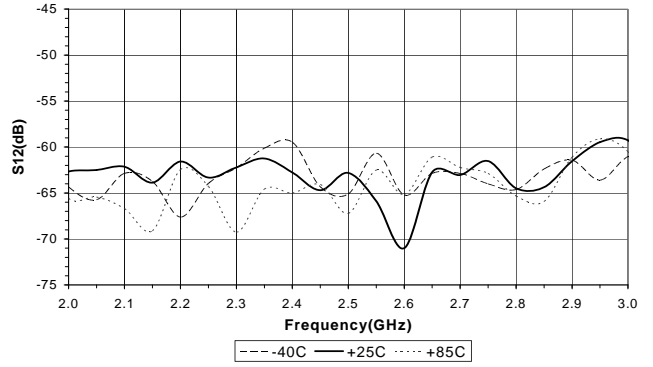


Measured 2.4GHz to 2.5GHz Application Circuit Data ( $V_{CC}=V_{PC}=5.0V$ ,  $I_Q=556mA$ ,  $T=25^\circ C$ )

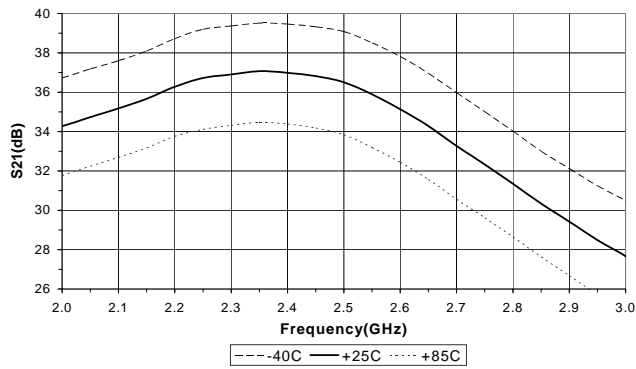
**Narrowband S11 - Input Return Loss**



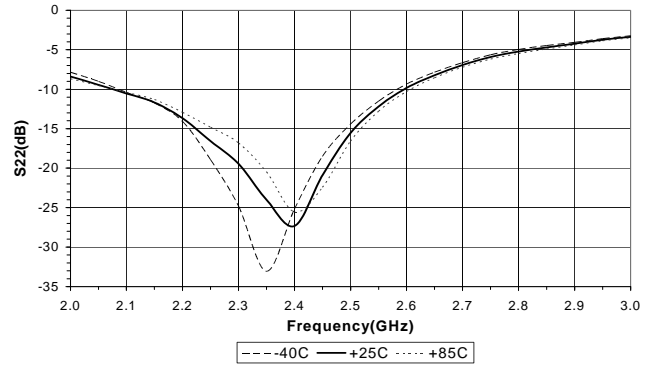
**Narrowband S12 - Reverse Isolation**



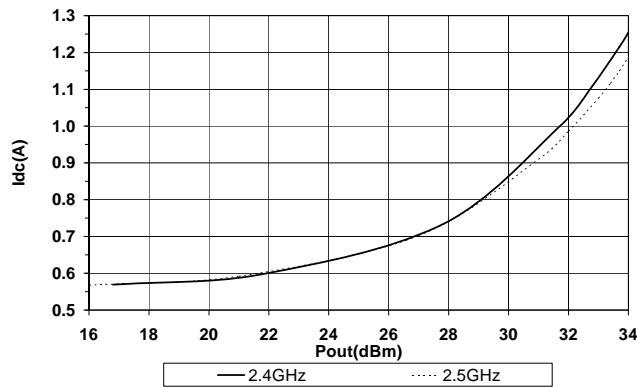
**Narrowband S21 - Forward Gain**



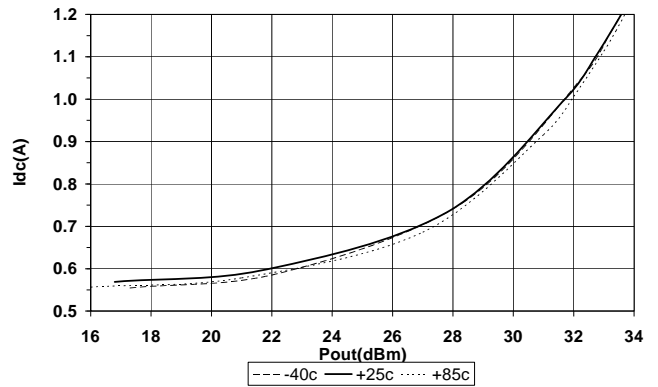
**Narrowband S22 - Output Return Loss**



**DC Supply Current vs Pout, T=+25C**

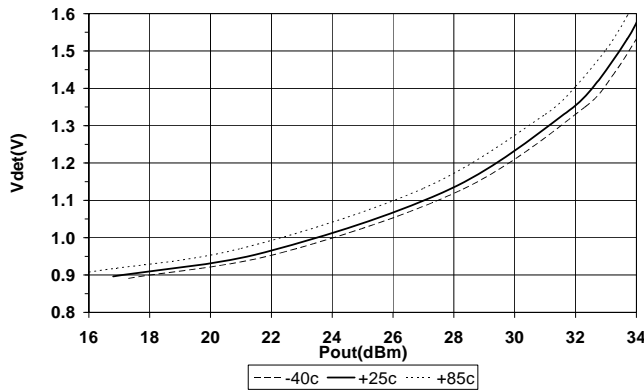


**DC Supply Current vs Pout, F=2.4GHz**

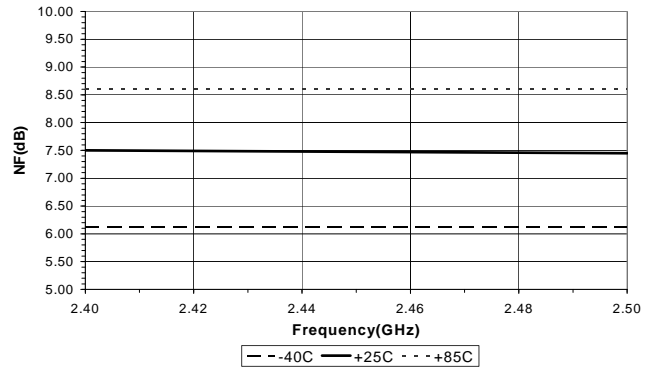


Measured 2.4GHz to 2.5GHz Application Circuit Data ( $V_{CC}=V_{PC}=5.0V$ ,  $I_Q=556mA$ ,  $T=25^\circ C$ )

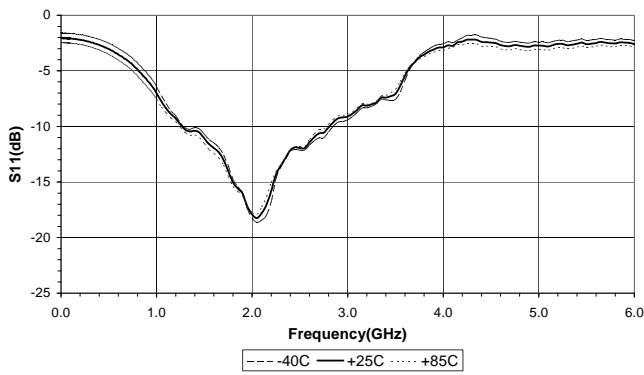
RF Power Detector (Vdet) vs Pout, F=2.4GHz



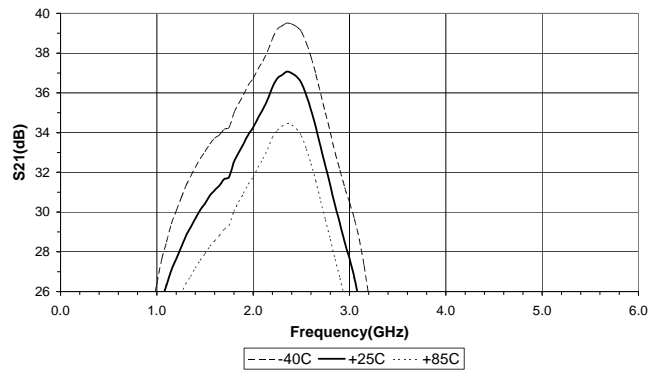
Noise Figure vs Frequency



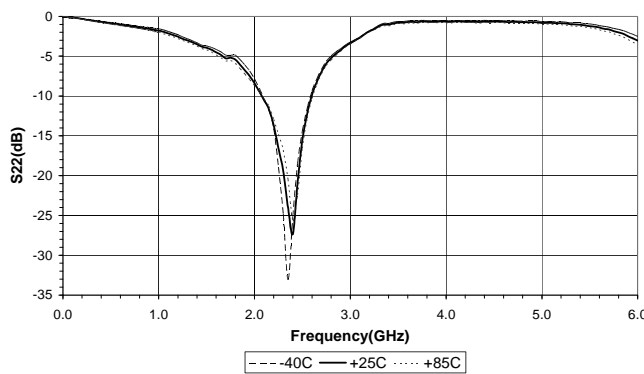
Broadband S11 - Input Return Loss



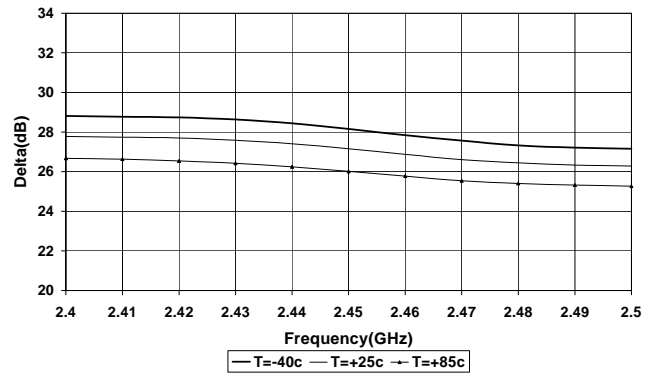
Broadband S21 - Forward Gain



Broadband S22 - Output Return Loss

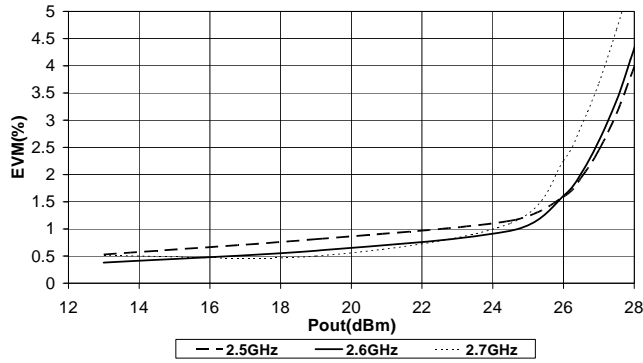


2.4-2.5GHz 20dB Step Attenuator Gain Delta vs Temp. Attenuator Enabled VPC2=0V

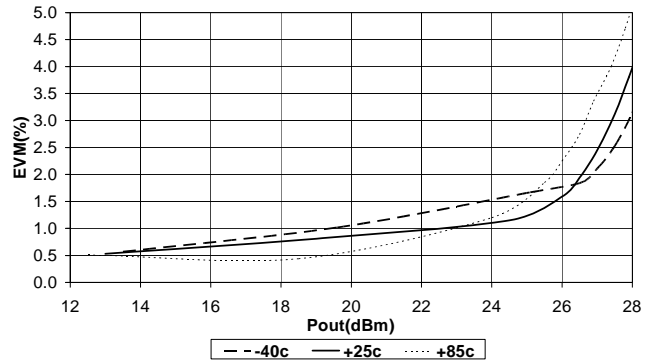


Measured 2.5GHz to 2.7GHz Application Circuit Data ( $V_{CC}=V_{PC}=5.0V$ ,  $I_Q=583mA$ ,  $T=25^\circ C$ )

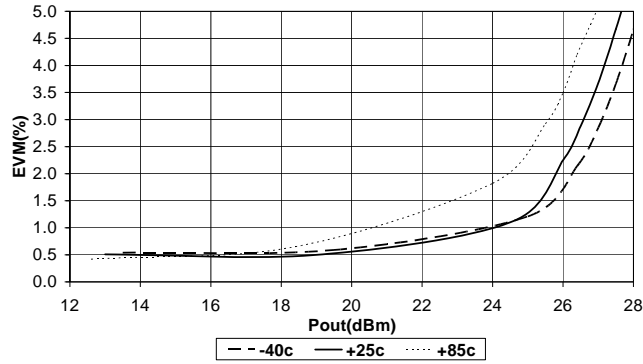
**EVM vs Pout T=+25c**  
802.11g, OFDM 54Mb/S, 64QAM



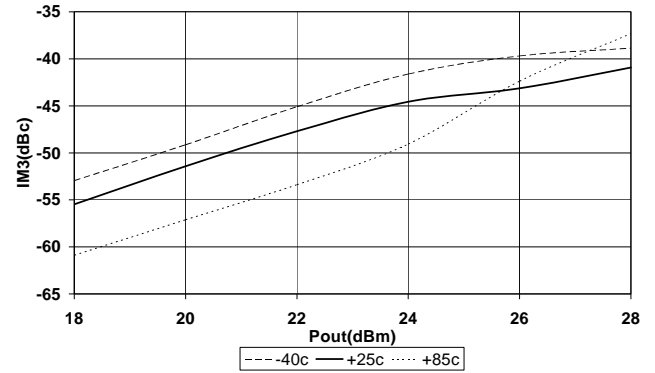
**EVM vs Pout F=2.5GHz**  
802.11g, OFDM 54Mb/S, 64QAM



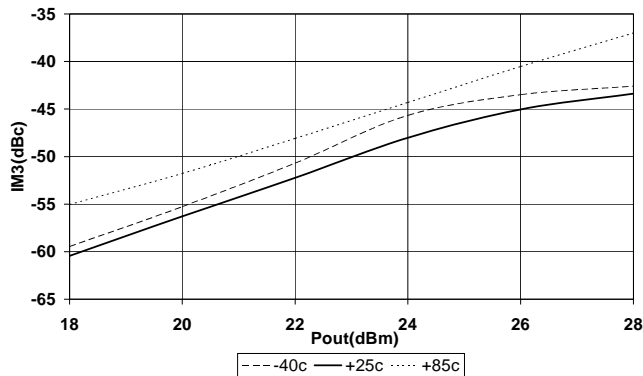
**EVM vs Pout F=2.7GHz**  
802.11g, OFDM 54Mb/S, 64QAM



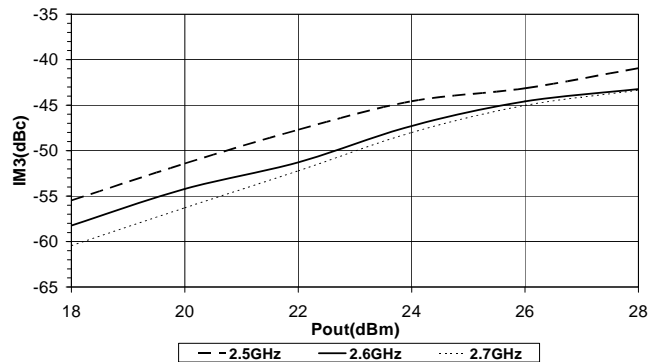
**IM3 vs Pout (2 tone avg.), F=2.5GHz**



**IM3 vs Pout (2 tone avg.), F=2.7GHz**

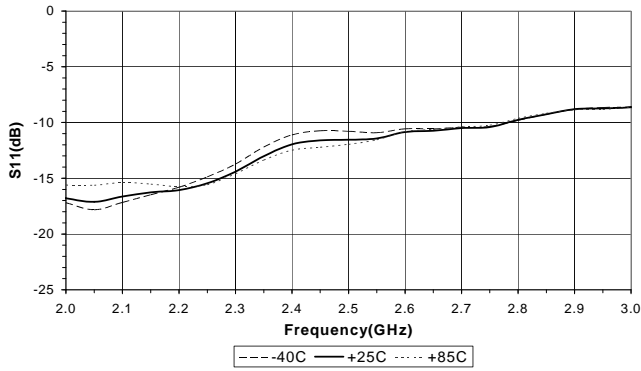


**IM3 vs Pout (2 Tone Avg.), T=+25c**  
Tone Spacing = 1MHz

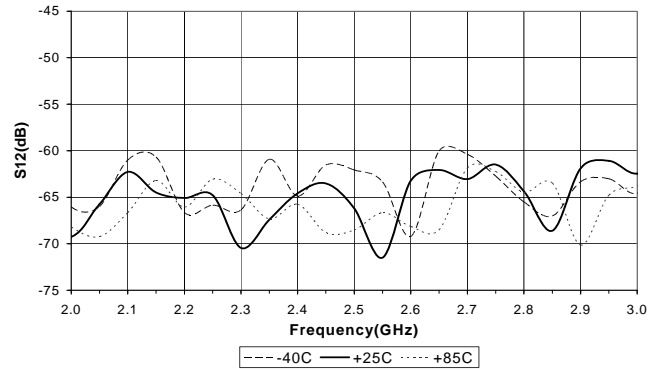


Measured 2.5GHz to 2.7GHz Application Circuit Data ( $V_{CC}=V_{PC}=5.0V$ ,  $I_Q=583mA$ ,  $T=25^\circ C$ )

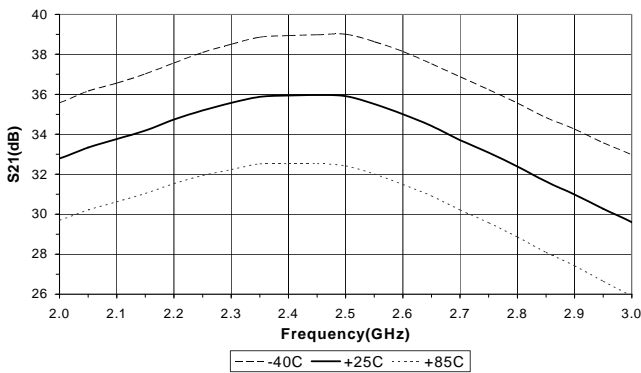
**Narrowband S11 - Input Return Loss**



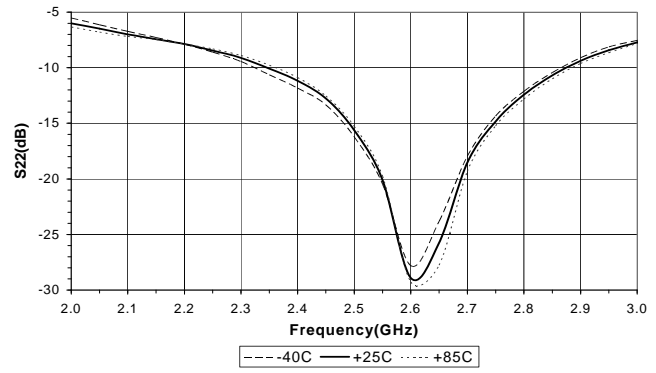
**Narrowband S12 - Reverse Isolation**



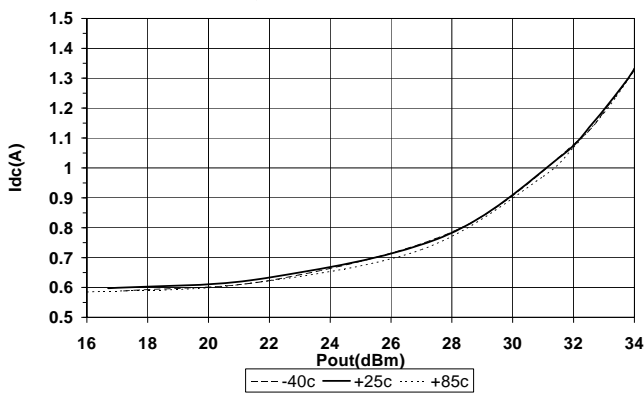
**Narrowband S21 - Forward Gain**



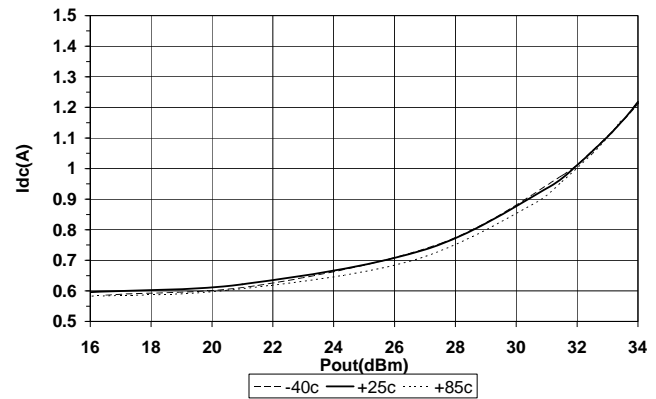
**Narrowband S22 - Output Return Loss**



**DC Supply Current vs Pout, F=2.5GHz**

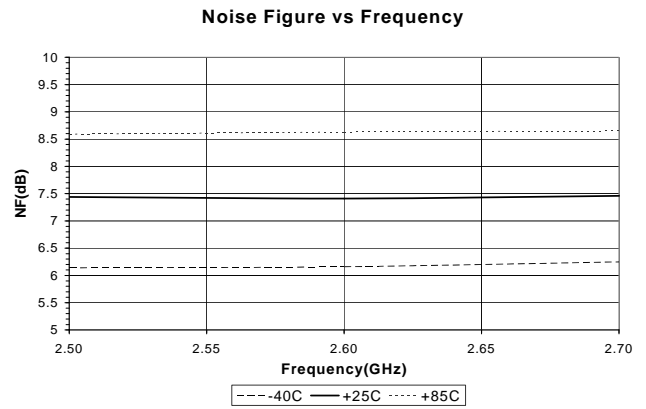
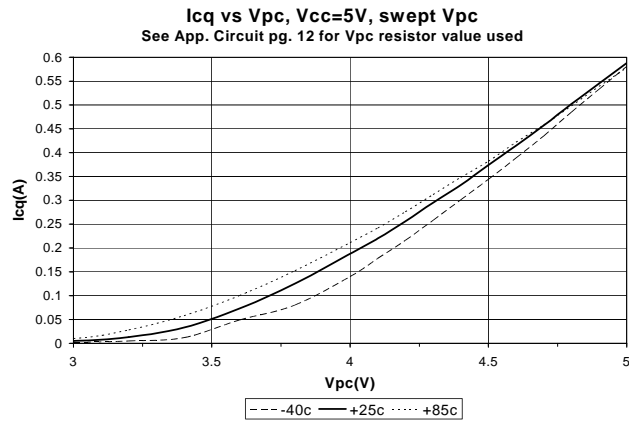
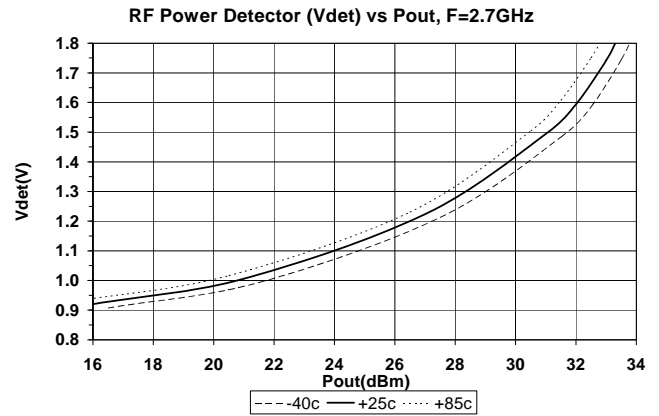
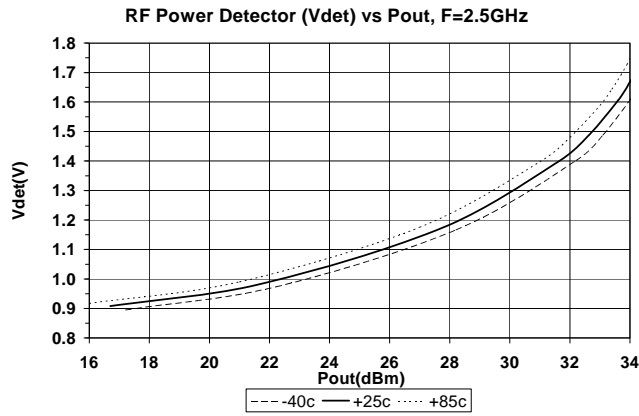


**DC Supply Current vs Pout, F=2.7GHz**



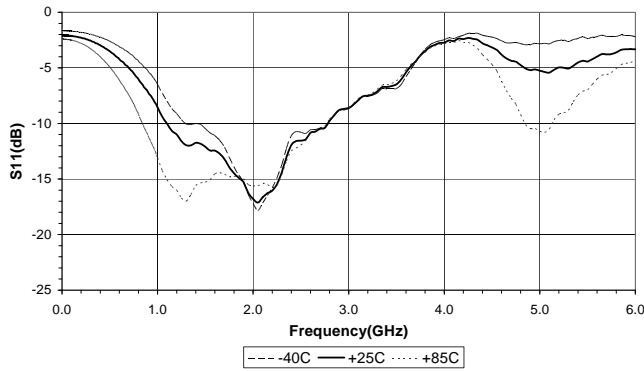


Measured 2.5GHz to 2.7GHz Application Circuit Data ( $V_{CC}=V_{PC}=5.0V$ ,  $I_Q=583mA$ ,  $T=25^\circ C$ )

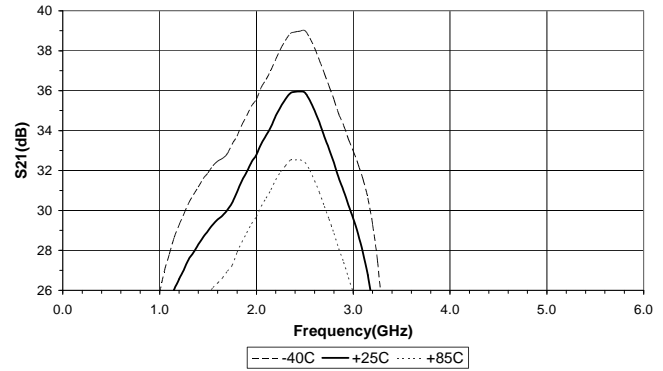


Measured 2.5GHz to 2.7GHz Application Circuit Data ( $V_{CC}=V_{PC}=5.0V$ ,  $I_Q=583mA$ ,  $T=25^\circ C$ )

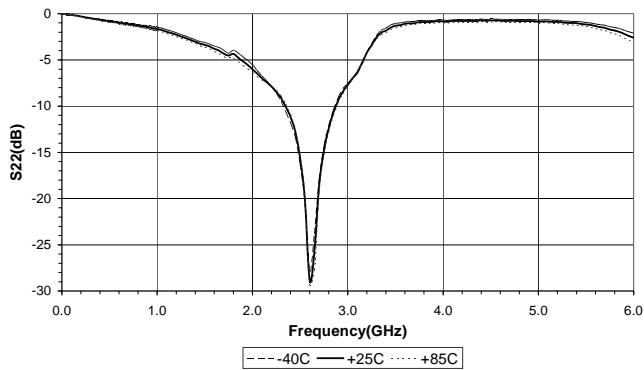
**Broadband S11 - Input Return Loss**



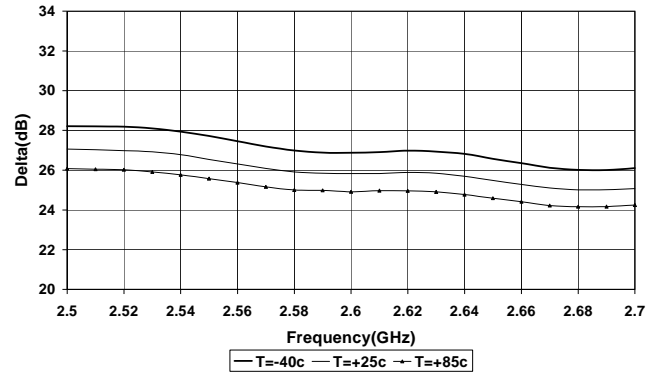
**Broadband S21 - Forward Gain**



**Broadband S22 - Output Return Loss**



**2.5-2.7GHz 20dB Step Attenuator Gain Delta vs Temp.  
Attenuator Enabled VPC2=0V**



| Pin                              | Function                                 | Description  |
|----------------------------------|--|--|
| 7, 11, 12, 22, 29, 31, 39, 40    | NC                                       | These are no connect (NC) pins and are not wired inside the package. It is recommended to connect them as shown in the application circuit to achieve the stated performance.  |
| 1, 10, 21, 30                    | GND                                      | These pins are internally grounded inside the package to the backside ground paddle. It is recommended to also ground them external to the package to achieve the specified performance.   |
| 2                                | VC1                                      | This is the collector of the first stage.  |
| 3                                | VBIAS12                                  | This is the supply voltage for the active bias circuit of the 1st and 2nd stages.  |
| 4-5                              | R1A-R2A                                  | A resistor is tied across these pins internal to the package.  |
| 6                                | RFIN                                     | This is the RF input pin. It is DC grounded inside the package. Do not apply DC voltage to this pin.   |
| 8                                | VPC1                                     | Power up/down control pin for the 1st stage. An external series resistor is required for proper setting of bias levels depending on control voltage. The voltage on this pin should never exceed the voltage on pin 3 by more than 0.5V unless the supply current from pin 3 is limited < 10mA.  |
| 9                                | VPC2                                     | Power up/down control pin for the 2nd stage. Power down $V_{PC2} < 1V$ for step attenuator function enable. An external series resistor is required for proper setting of bias levels depending on control voltage. The voltage on this pin should never exceed the voltage on pin 3 by more than 0.5V unless the supply current from pin 3 is limited < 10mA. |
| 13, 38                           | VC2A, VC2B                               | These two pins are connected internal to the package and connect to the 2nd stage collector. To achieve specified performance, the layout of these pins should match the Recommended Land Pattern.   |
| 14-15<br>17-18<br>33-34<br>36-37 | C1A-C2A<br>C3A-C4A<br>C4B-C3B<br>C2B-C1B | These pins have capacitors across them internal to the package as shown in the below schematic. They are used as tuning and RF coupling elements between the 2nd and 3rd stage.  |
| 16, 35                           | VB3A, VB3B                               | These are the connections to the base of the 3rd stage output device. To achieve specified performance, the layout of these pins should match the Recommended Land Pattern.  |
| 19                               | VPC3                                     | Power up/down control pin for the 2nd stage. An external series resistor is required for proper setting of bias levels depending on control voltage. The voltage on this pin should never exceed the voltage on pin 32 by more than 0.5V unless the supply current from pin 33 is limited < 10mA.  |
| 20                               | VDET                                     | This is the output port for the power detector. It samples the power at the input of the 3rd stage.  |
| 23-28                            | RFOUT                                    | These are the RF output pins and DC connections to the 3rd stage collector.  |
| 32                               | VBIAS3                                   | This is the supply voltage for the active bias circuit of the 3rd stage.   |

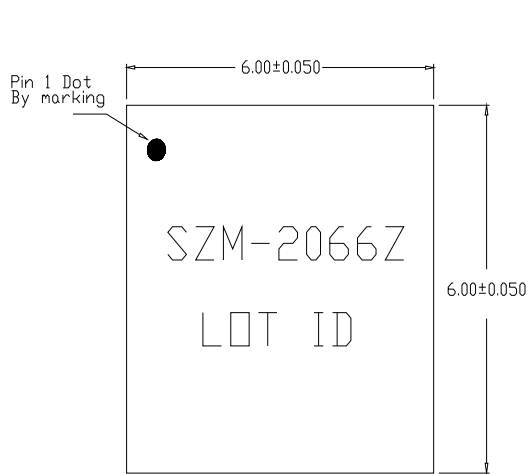
## Part Symbolization

The part will be symbolized with “SZM-2066Z” to designate it as a RoHS green compliant product. Marking designator will be on the top surface of the package.

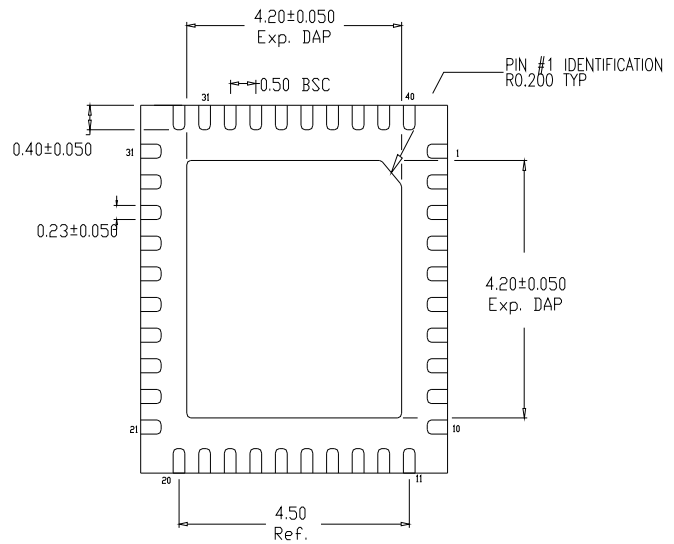
## Package Drawing

Dimensions in inches (millimeters)

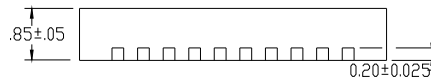
Refer to drawing posted at [www.rfmd.com](http://www.rfmd.com) for tolerances.



TOP VIEW

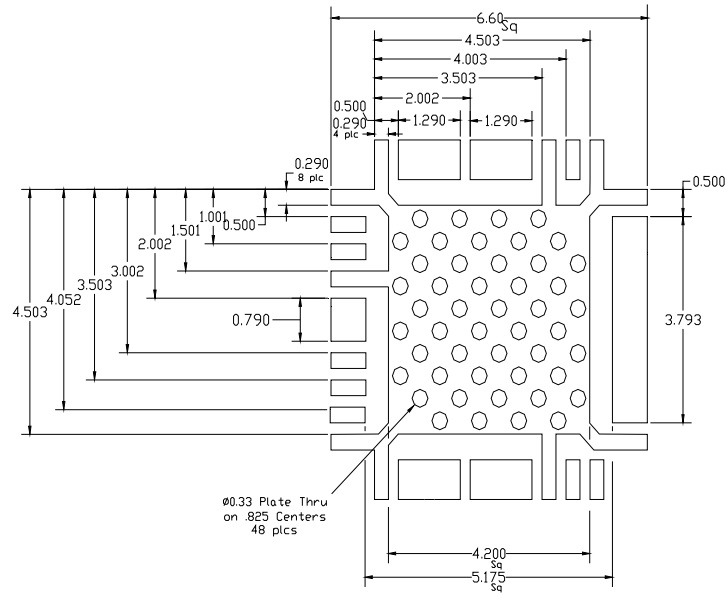


BOTTOM VIEW

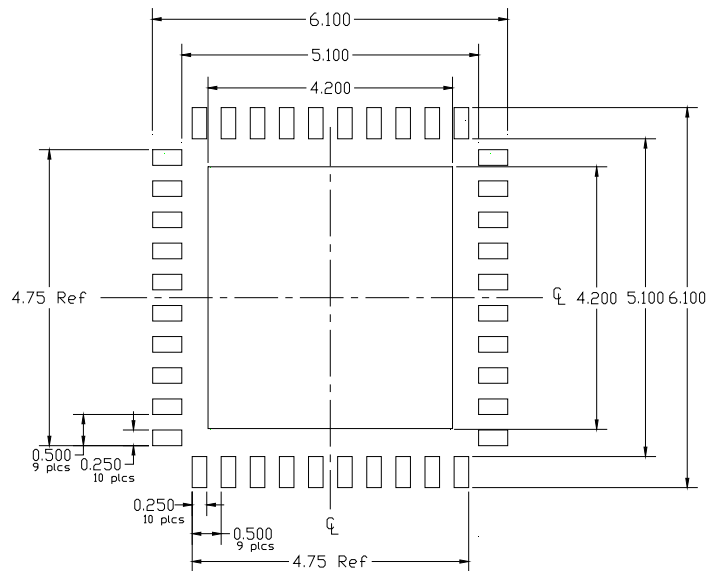


SIDE VIEW

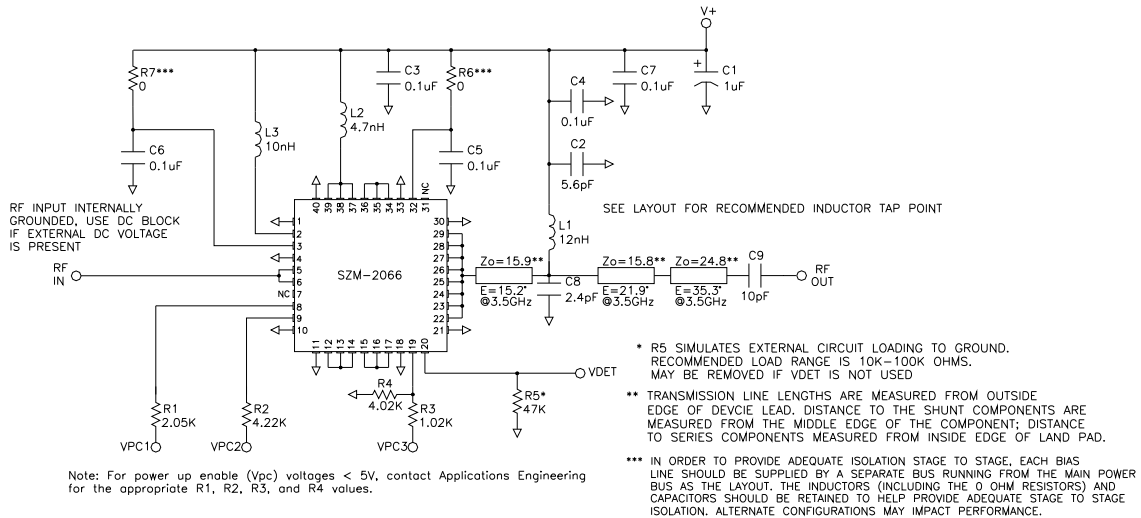
**Recommended Metal Land Pattern**



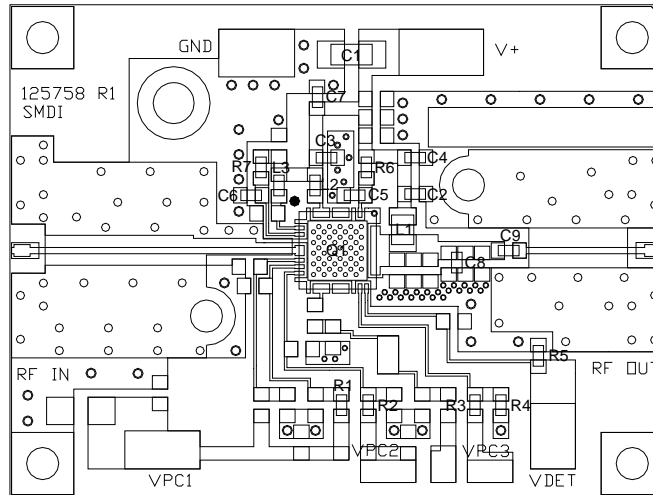
**Recommended PCB Soldermask for Land Pattern**



## 2.4GHz to 2.5GHz Evaluation Board Schematic for $V_{CC}=V+=V_{PC}=5.0V$



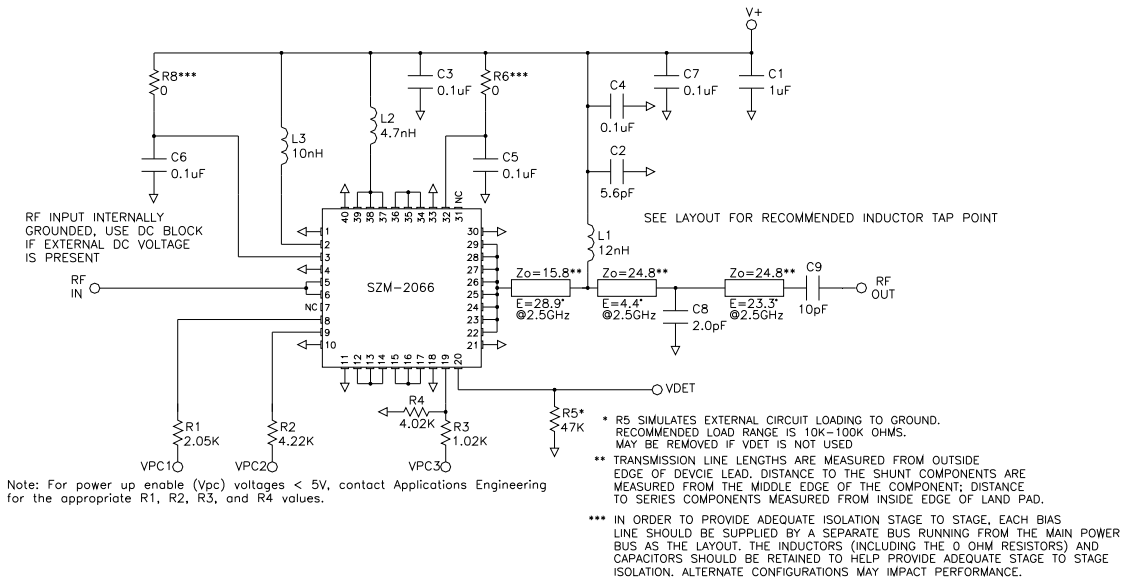
**2.4GHz to 2.5GHz Evaluation Board for  $V_{CC}=V_{+}=V_{PC}=5.0V$**



**Bill of Materials for the 2.4GHz to 2.5GHz Evaluation Board**

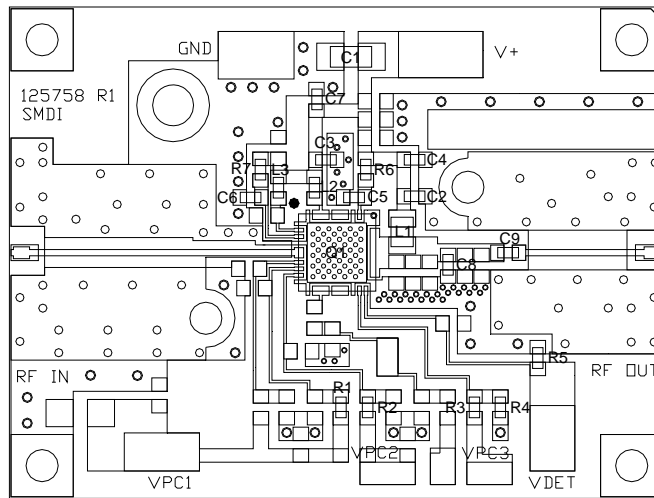
| Desg           | Description              | Notes   |
|----------------|--------------------------|---|
| Q1             | SZM-2066Z                | 6mmx6mm QFN   |
| R1             | 2.05K $\Omega$ , 0603 1% | 0402 may be used  |
| R2             | 4.22K $\Omega$ , 0603 1% | 0402 may be used  |
| R3             | 1.02K $\Omega$ , 0603 1% | 0402 may be used  |
| R4             | 4.02K $\Omega$ , 0603 1% | 0402 may be used  |
| R5             | 47 K $\Omega$ , 0603     | 0402 may be used  |
| R6, 7          | 0 $\Omega$ , 0603        | 0402 may be used  |
| C1             | 1 $\mu$ F 16V MLCC CAP   | Tantalum ok for EVM performance. Use MLCC type for best IM3 levels. |
| C2             | 5.6pF CAP, 0603          | NPO, ROHM MCH185A5R6DK or equivalent                                |
| C3, 4, 5, 6, 7 | 0.1 $\mu$ F CAP, 0603    | X7R 0402 ok, ROHM MCH182CN104K or equivalent                        |
| C8             | 2.4pF CAP, 0603          | NPO, low ESR, ATC 60052R4CW250 or equivalent                        |
| C9             | 10pF CAP, 0603           | X7R 0402 ok, ROHM MCH1182CN104K or equivalent                       |
| L1             | 12nH IND 0805            | Coilcraft 0805HQ - 12XJBB   |
| L2             | 4.7nH IND, 0603          | TOKO 0603 - LL1608FH4N7J  |
| L3             | 10nH IND, 0603           | TOKO 0603 - LL1608FH10J   |

## 2.5GHz to 2.7GHz Evaluation Board Schematic for $V_{CC}=V+=V_{PC}=5.0V$





**2.5GHz to 2.7GHz Evaluation Board for  $V_{CC}=V+=V_{PC}=5.0V$**



**Bill of Materials for the 2.5GHz to 2.7GHz Evaluation Board**

| Desg           | Description              | Notes   |
|----------------|--------------------------|---|
| Q1             | SZM-2066Z                | 6mmx6mm QFN   |
| R1             | 2.05K $\Omega$ , 0603 1% | 0402 may be used  |
| R2             | 4.22K $\Omega$ , 0603 1% | 0402 may be used  |
| R3             | 1.02K $\Omega$ , 0603 1% | 0402 may be used  |
| R4             | 4.02K $\Omega$ , 0603 1% | 0402 may be used  |
| R5             | 47 K $\Omega$ , 0603     | 0402 may be used  |
| R6, 7          | 0 $\Omega$ , 0603        | 0402 may be used  |
| C1             | 1 $\mu$ F 16V MLCC CAP   | Tantalum ok for EVM performance. Use MLCC type for best IM3 levels. |
| C2             | 5.6pF CAP, 0603          | NPO, ROHM MCH185A5R6DK or equivalent                                |
| C3, 4, 5, 6, 7 | 0.1 $\mu$ F CAP, 0603    | X7R 0402 ok, ROHM MCH182CN104K or equivalent                        |
| C8             | 2.4pF CAP, 0603          | NPO, low ESR, ATC 60052R4CW250 or equivalent                        |
| C9             | 10pF CAP, 0603           | NPO, low ESR, ATC 600S100JW250 or equivalent                        |
| L1             | 12nH IND 0805            | Coilcraft 0805HQ - 12XJBB   |
| L2             | 4.7nH IND, 0603          | TOKO 0603 - LL1608FH4N7J  |
| L3             | 10nH IND, 0603           | TOKO 0603 - LL1608FH10J   |

## Ordering Information

| Ordering Code    | Description   |
|------------------|---|
| SZM2066ZSQ       | Standard 25 piece bag   |
| SZM2066ZSR       | Standard 100 piece reel   |
| SZM2066Z         | Standard 1000 piece reel  |
| SZM2066ZPCK-EVB2 | Evaluation Board 2.4GHz to 2.5GHz Tune and 5 loose sample pieces  |
| SZM2066ZPCK-EVB3 | Evaluation Board 2.5GHz to 2.7 GHz Tune and 5 loose sample pieces |

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